## MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	VCEO	30	Vdc
Collector-Base Voltage	V <sub>CBO</sub>	60	Vdc
Emitter-Base Voltage	VEBO	3.0	Vdc
Collector Current — Continuous	۱c	1.0	Adc
Total Device Dissipation @ T <sub>C</sub> = 25°C(1) Derate above 25°C	PD	5.0 28.6	Watts mW/°C
Storage Temperature	Tsta	-65 to +200	°C

**MRF8004** CASE 79-02, STYLE 1

TO-39 (TO-205AD)

## **RF AMPLIFIER TRANSISTOR**

NPN SILICON

14

(1) This device is designed for RF operation. The total device dissipation rating applies only when the device is operated as an RF amplifier.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted.)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = 50 mAdc, I <sub>B</sub> = 0)	V(BR)CEO	30	-	—	Vdc
Collector-Emitter Breakdown Voltage (I <sub>C</sub> = 200 mAdc, V <sub>BE</sub> = 0)	V(BR)CES		-	-	Vdc
Emitter-Base Breakdown Voltage (I <sub>E</sub> = 1.0 mAdc, I <sub>C</sub> = 0)	V(BR)EBO	3.0	—	-	Vdc
Collector Cutoff Current (V <sub>CB</sub> = 15 Vdc, $I_E = 0$ )	<sup>I</sup> СВО	—	—	0.01	mAdc
ON CHARACTERISTICS					
DC Current Gain $(I_C = 400 \text{ mAdc}, V_{CE} = 2.0 \text{ Vdc})$	hFE	10	_	—	-
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance (V <sub>CB</sub> = 12.5 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	C <sub>obo</sub>	—	35	70	pF
FUNCTIONAL TEST					
Common-Emitter Amplifier Power Gain (See Figure 1) (P <sub>out</sub> = 3.5 W, V <sub>CC</sub> = 12.5 Vdc, f = 27 MHz)	GPE	10	-	-	dB
Collector Efficiency(2) (See Figure 1) (P <sub>out</sub> = 3.5 W, V <sub>CC</sub> = 12.5 Vdc, f = 27 MHz)	η	62.5	70	-	%
Percentage Up-Modulation(1) (See Figure 1) (f = 27 MHz)	_	_	85	-	%
Parallel Equivalent Input Resistance (P <sub>OUt</sub> = 3.5 W, V <sub>CC</sub> = 12.5 Vdc, f = 27 MHz)	R <sub>in</sub>	_	21	—	Ohms
Parallel Equivalent Input Capacitance (P <sub>out</sub> = 3.5 W, V <sub>CC</sub> = 12.5 Vdc, f = 27 MHz)	C <sub>in</sub>	-	900	_	pF
Parallel Equivalent Output Capacitance (P <sub>out</sub> = 3.5 W, V <sub>CC</sub> = 12.5 Vdc, f = 27 MHz)	C <sub>out</sub>	—	200		pF

(1) Percentage Up-Modulation is measured in the test circuit (Figure 1) by setting the Carrier Power (P<sub>C</sub>) to 3.5 Watts with V<sub>CC</sub> = 12.5 Vdc and noting the power input. Then the Peak Envelope Power (PEP) is noted after doubling the original power input to simulate driver modulation (at a 25% duty cycle for thermal considerations) and raising the V<sub>CC</sub> to 25 Vdc (to simulate the modulating voltage). Percentage Up-Modulation is then determined by the relation:

modulation (at a 25% duty cycle for thermal considerations) an Percentage Up-Modulation is then determined by the relation: Percentage Up-Modulation =  $\left[\left(\frac{PEP}{P_{C}}\right)^{\frac{1}{2}} - 1\right] \cdot 100$ (2)  $\eta = \frac{RFP_{OUL}}{(V_{CC})(I_{C})} \cdot 100$ 

## **MRF8004**

FIGURE 1 - 27 MHz TEST CIRCUIT





FIGURE 3 - CIRCUIT TUNED AT 12.5 V, Pout = 4 W

